



MICROBOND®



Microbond® SMT660 Innolot® No-Clean Printing T4 Solder Paste

Microbond® SMT660 Innolot® paste stands for highly reliable, high-performance paste with a competitive Total Cost of Ownership (TCO) offering. Innolot® is a well-known alloy, allowing for higher creep resistance, resulting in longer product life-cycles at higher operating temperatures. The SMT660 Innolot® solder paste performs in air without additional N₂ during reflow, while keeping defects low, reducing your TCO. This specifically means reduced pin and blowhole behavior, very low BGA voiding and low area voiding.

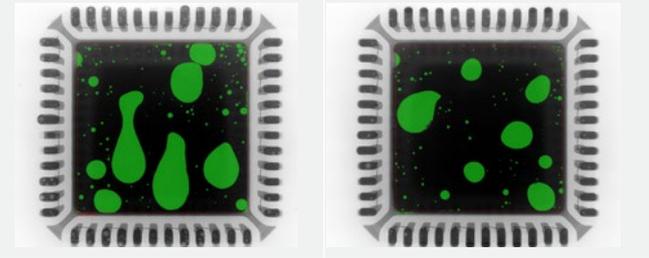
Key Features

- Innolot® solder paste solderable in air with low defects
- Acrylic-based synthetic resin ensuring stable quality
- Reduced pin and blowhole behavior
- High reliability alloy and high SIR performance
- Low area voiding
- Halogen zero

Voiding example on MLF 48 processed in air

Conventional Innolot® solder paste

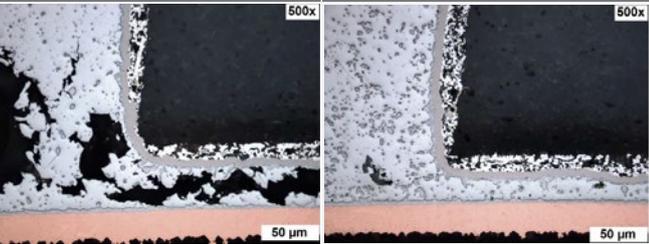
SMT660 Innolot®



Cross section on a 1206 resistor after 2000 hours temperature cycling test from -40 °C to 125 °C

SAC305

Innolot®



Product properties Microbond® SMT660 Innolot®

Alloy	Innolot®
Metal content	89%
Powder type	Type 4
Halogen content	Halogen zero
Flux classification	No-clean

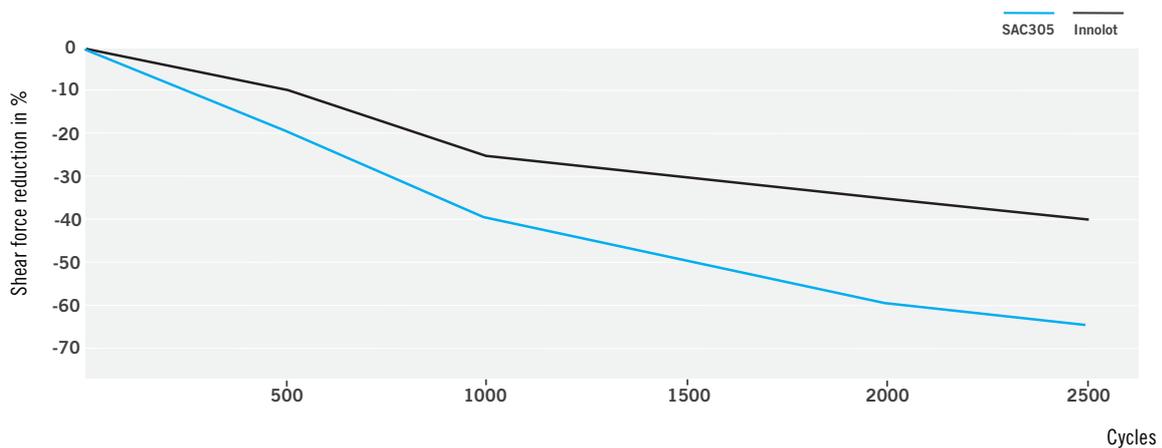
Powder properties

Particle size	20 - 38 µm
Alloy	Sn/Ag3.8/Cu0.7/Ni0.15/Sb1.5/Bi3
Melting point	206 - 218 °C

Storage

Temperature	2 - 10 °C
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Reliability on chip resistor 1206 with chemical tin finish and temperature cycling from -40 °C to 125 °C



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